

DB2S309

Silicon epitaxial planar type

For high speed switching circuits
DB2J309 in SSMini2 type package

■ Features

- Small reverse current I_R
- Short reverse recovery time t_{rr}
- Halogen-free / RoHS compliant
(EU RoHS / UL-94 V-0 / MSL: Level 1 compliant)

■ Marking Symbol:C5

■ Packaging

DB2S30900L Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	30	V
Repetitive peak reverse voltage	V_{RRM}	30	V
Forward current (Average)	$I_{F(AV)}$	100	mA
Peak forward current	I_{FM}	200	mA
Non-repetitive peak forward surge current *1	I_{FSM}	1	A
Junction temperature	T_j	125	$^\circ\text{C}$
Operating ambient temperature	T_{opr}	-40 to +85	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +125	$^\circ\text{C}$

Note) *1: 50 Hz sine wave 1 cycle (Non-repetitive peak current)

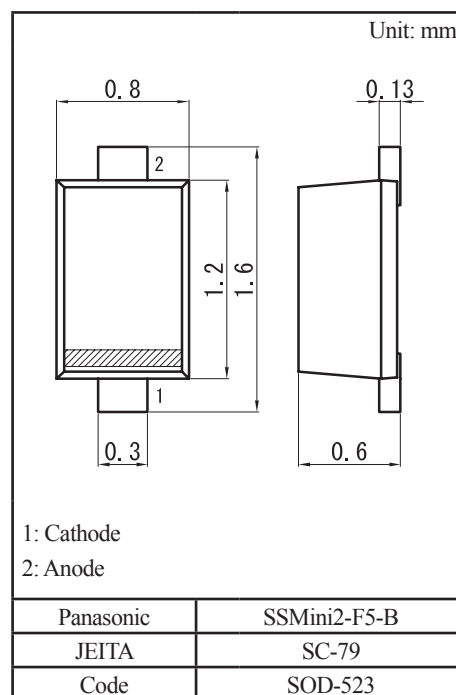
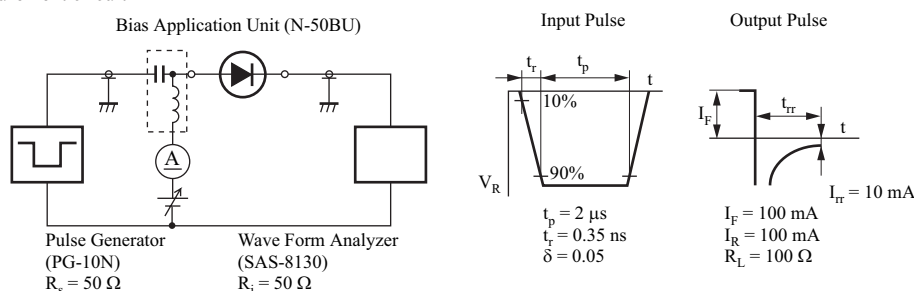
■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

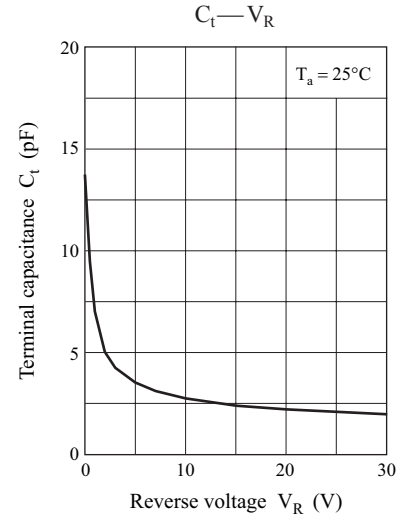
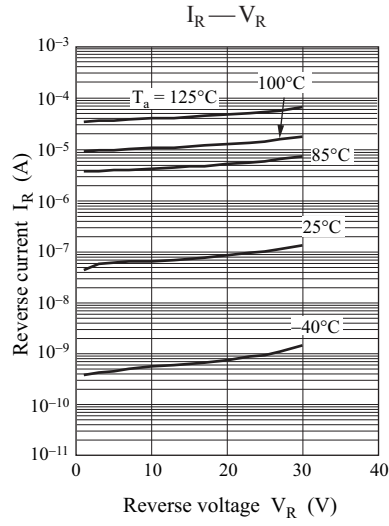
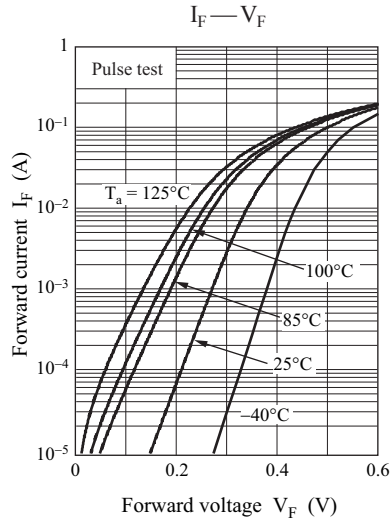
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_{F1}	$I_F = 10 \text{ mA}$			0.44	V
	V_{F2}	$I_F = 100 \text{ mA}$			0.58	
Reverse current	I_{R1}	$V_R = 10 \text{ V}$			0.3	μA
	I_{R2}	$V_R = 30 \text{ V}$			2.0	
Terminal capacitance	C_t	$V_R = 10 \text{ V}, f = 1 \text{ MHz}$		3.0		pF
Reverse recovery time *1	t_{rr}	$I_F = I_R = 100 \text{ mA}, I_{tr} = 10 \text{ mA}, R_L = 100 \Omega$		1.3		ns

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
3. Absolute frequency of input and output is 250 MHz

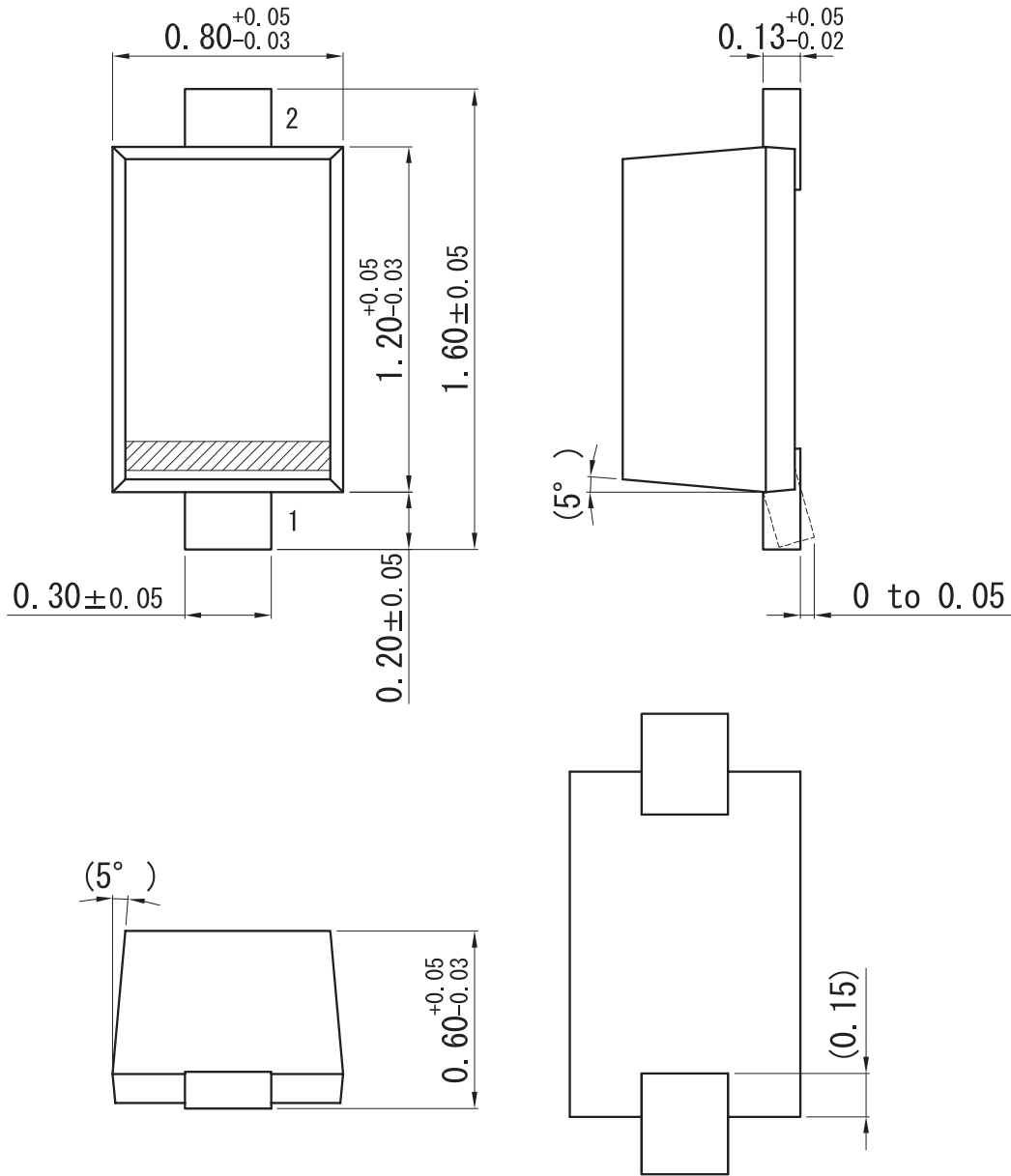
*1: t_{rr} measurement circuit



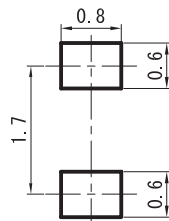


SSMini2-F5-B

Unit: mm



■ Land Pattern (Reference) (Unit: mm)



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